

Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 1 October 2020 [Approved on 31 May 2021, 12:57 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	11.5%	Gold	7440-57-5	8.5%
			ALUMINIUM	7429-90-5	12%
			Silicon	7440-21-3	79.5%
Die attach	Gold	3.5%	Tin	7440-31-5	20%
			Gold	7440-57-5	80%
Encapsulation	EP (Epoxy resin)	47.2%	Carbon black	1333-86-4	0.3%
			Crystallized silicon dioxide	14808-60-7	0.8%
			2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane	1675-54-3	0.99%
			Epoxy resin 89	26335-32-0	27.61%
			Quartz sand	60676-86-0	70.3%
Inner preparation	Gold	1.5%	Gold	7440-57-5	100%
Leadfinish	Tin plating	5.3%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	31%	Magnesium	7439-95-4	0.2%
			Nickel	7440-02-0	2.8%
			Copper	7440-50-8	97%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
QFN2x2	Diode/Transistor SMD	0.05	g

